NTB5605P, NTBV5605

[MOSFET](#) – Power, P-Channel, D²PAK

-60 V, -18.5 A

Features
- Designed for Low $R_{DS(on)}$
- Withstands High Energy in Avalanche and Commutation Modes
- AEC Q101 Qualified – NTBV5605
- These Devices are Pb−Free and are RoHS Compliant

Applications
- Power Supplies
- PWM Motor Control
- Converters
- Power Management

$V_{(BR)DSS}$	$R_{DS(on)}$ TYP	I_D MAX
–60 V	120 mΩ @ –5.0 V	–18.5 A

P−Channel

MARKING DIAGRAM & PIN ASSIGNMENT

**D²PAK
CASE 418B
STYLE 2**

4
Drain

NTB5605xG
AYWW

1 — Gate
2 — Drain
3 — Source

x	= P or blank
A	= Assembly Location
Y	= Year
WW	= Work Week
G	= Pb−Free Package

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter	Symbol			Value	Unit
Drain−to−Source Voltage			V_{DSS}	–60	V
Gate−to−Source Voltage			V_{GS}	±20	V
Continuous Drain Current (Note 1)	Steady State	T_A = 25°C	I_D	–18.5	A
Power Dissipation (Note 1)	Steady State	T_A = 25°C	P_D	88	W
Pulsed Drain Current	t_p = 10 μs		I_{DM}	–55	A
Operating Junction and Storage Temperature			T_J, T_{STG}	–55 to 175	°C
Single Pulse Drain−to−Source Avalanche Energy (V_{DD} = 25 V, V_{GS} = 5.0 V, I_{PK} = 15 A, L = 3.0 mH, R_G = 25 Ω)			E_{AS}	338	mJ
Lead Temperature for Soldering Purposes (1/8 in from case for 10 s)			T_L	260	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction−to−Case (Drain) − Steady State	$R_{\theta JC}$	1.7	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
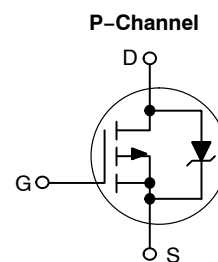1. When surface mounted to an FR4 board using 1″ pad size (Cu Area 1.127 in²).
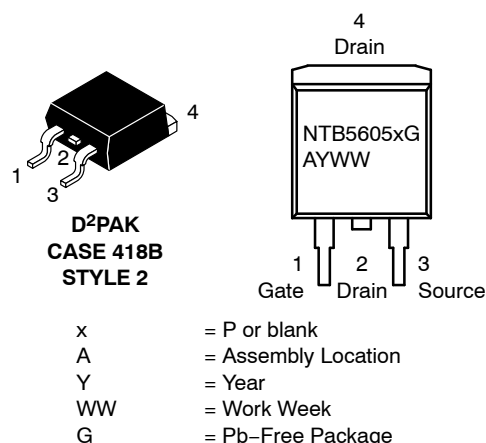2. When surface mounted to an FR4 board using the minimum recommended pad size (Cu Area 0.41 in²).

ORDERING INFORMATION

Device	Package	Shipping[†]
NTB5605PT4G	D²PAK (Pb−Free)	800 / Tape & Reel
NTBV5605T4G	D²PAK (Pb−Free)	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristic	Symbol	Test Condition		Min	Typ	Max	Unit
OFF CHARACTERISTICS							
Drain−to−Source Breakdown Voltage	$V_{(Br)DSS}$	V_{GS} = 0 V, I_D = −250 μA		−60			V
Drain−to−Source Breakdown Voltage Temperature Coefficient	$V_{(Br)DSS}/T_J$				−64		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V	T_J = 25°C			−1.0	μA
		V_{DS} = −60 V	T_J = 125°C			−10	
Gate−to−Source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±20 V				±100	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS} = V_{DS}, I_D = −250 μA		−1.0	−1.5	−2.0	V
Drain−to−Source On Resistance	$R_{DS(on)}$	V_{GS} = −5.0 V, I_D = −8.5 A V_{GS} = −5.0 V, I_D = −17 A			120 140	140	mΩ
Forward Transconductance	g_{FS}	V_{DS} = −10 V, I_D = −8.5 A			12		S
Drain−to−Source On Voltage	$V_{DS(on)}$	V_{GS} = −5.0 V, I_D = −8.5 A				−1.3	V
CHARGES, CAPACITANCES AND GATE RESISTANCE							
Input Capacitance	C_{iss}	V_{GS} = 0 V, f = 1.0 MHz, V_{DS} = −25 V			730	1190	pF
Output Capacitance	C_{oss}				211	300	
Reverse Transfer Capacitance	C_{rss}				67	120	
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = −5.0 V, V_{DS} = −48 V, I_D = −17 A			13	22	nC
Gate−to−Source Charge	Q_{GS}				4.0		
Gate−to−Drain Charge	Q_{GD}				7.0		
SWITCHING CHARACTERISTICS (Note 4)							
Turn−On Delay Time	$t_{d(on)}$	V_{GS} = −5.0 V, V_{DD} = −30 V, I_D = −17 A, R_G = 9.1 Ω			12.5	25	ns
Rise Time	t_r				122	183	
Turn−Off Delay Time	$t_{d(off)}$				29	58	
Fall Time	t_f				75	150	
DRAIN−SOURCE DIODE CHARACTERISTICS							
Forward Diode Voltage	V_{SD}	V_{GS} = 0 V I_S = −17 A	T_J = 25°C		−1.55	−2.5	V
			T_J = 125°C		−1.4		
Reverse Recovery Time	t_{rr}	V_{GS} = 0 V, dI_S/dt = 100 A/μs, I_S = −17 A			60		ns
Charge Time	t_a				39		
Discharge Time	t_b				21		
Reverse Recovery Charge	Q_{RR}				0.14		nC

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
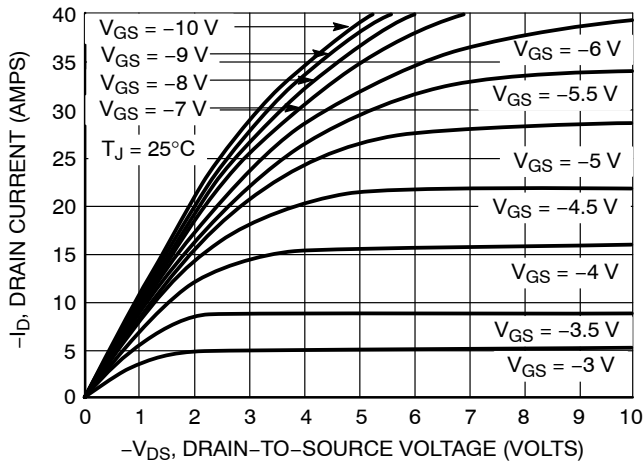4. Switching characteristics are independent of operating junction temperatures.

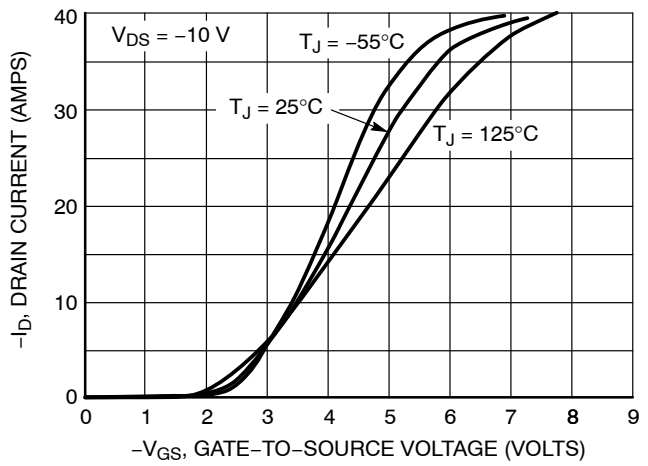Figure 1. On−Region Characteristics

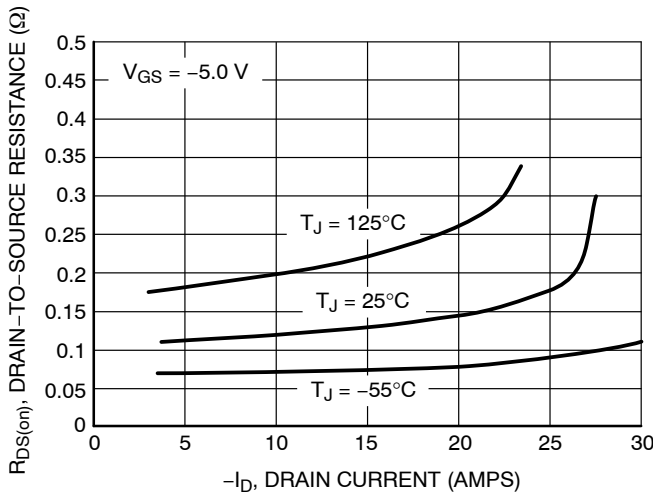Figure 2. Transfer Characteristics

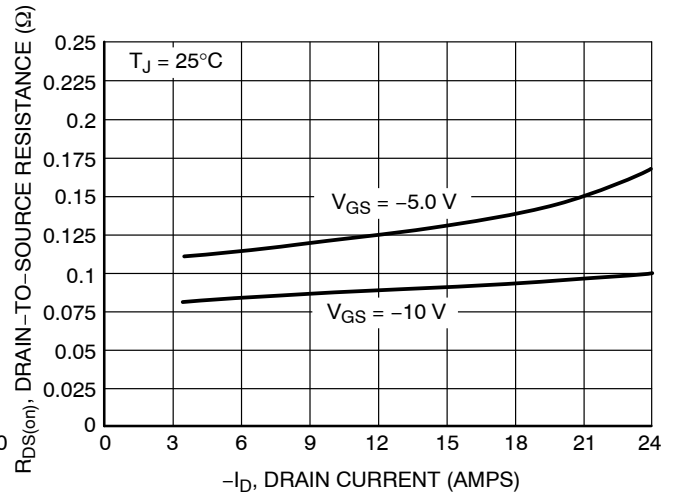Figure 3. On−Resistance vs. Drain Current and
Temperature

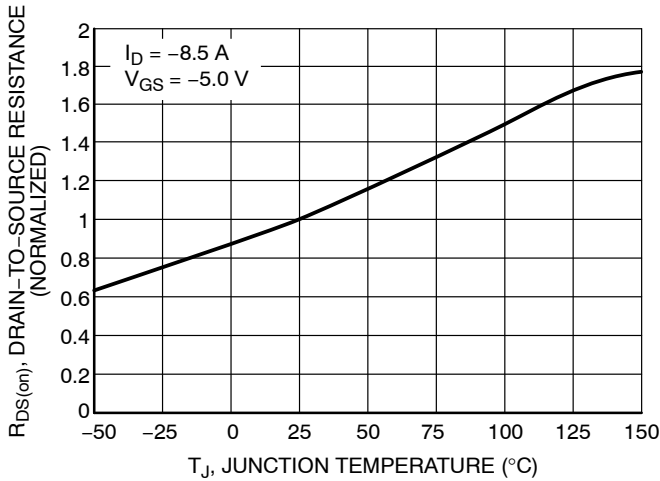Figure 4. On−Resistance vs. Drain Current and
Gate Voltage

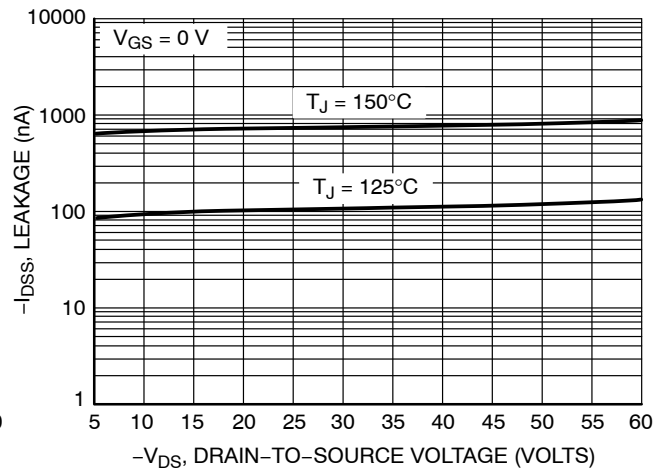Figure 5. On−Resistance Variation with
Temperature

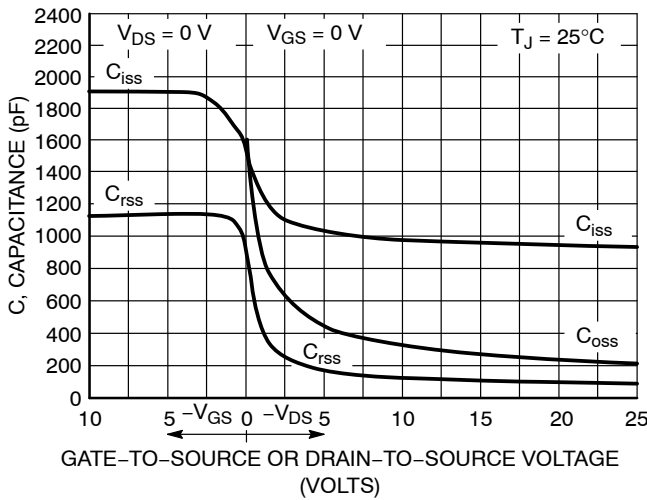Figure 6. Drain−to−Source Leakage Current
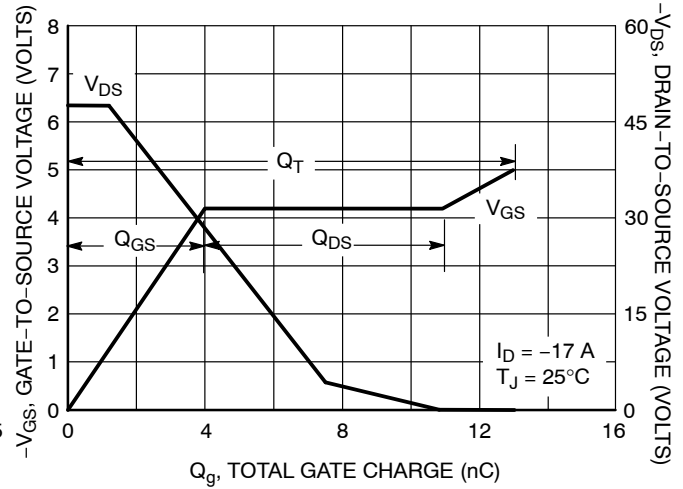vs. Voltage

Figure 7. Capacitance Variation

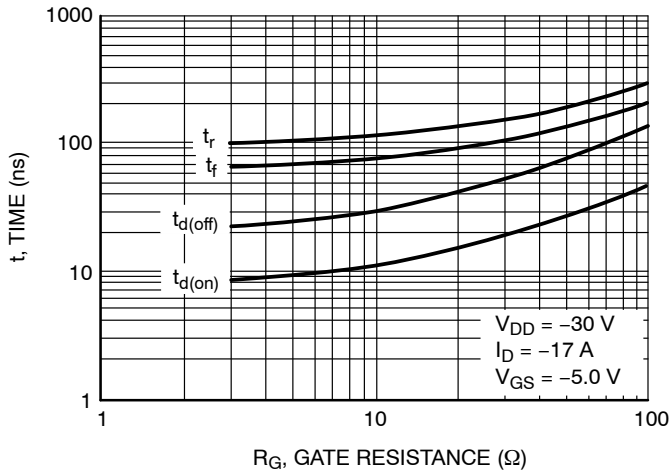**Figure 8. Gate–to–Source and Drain–to–Source Voltage vs. Total Charge**

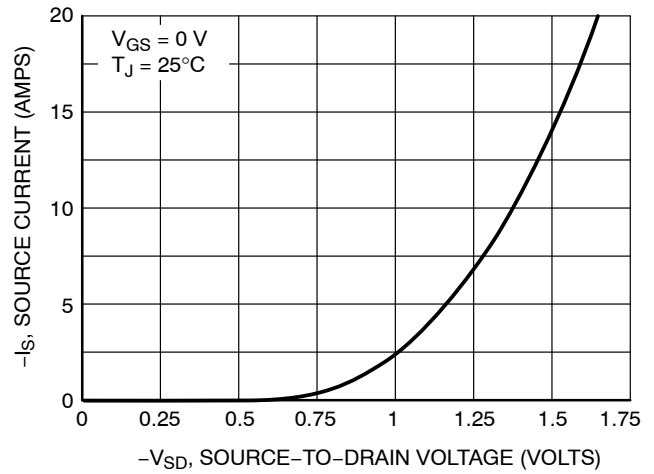
Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current
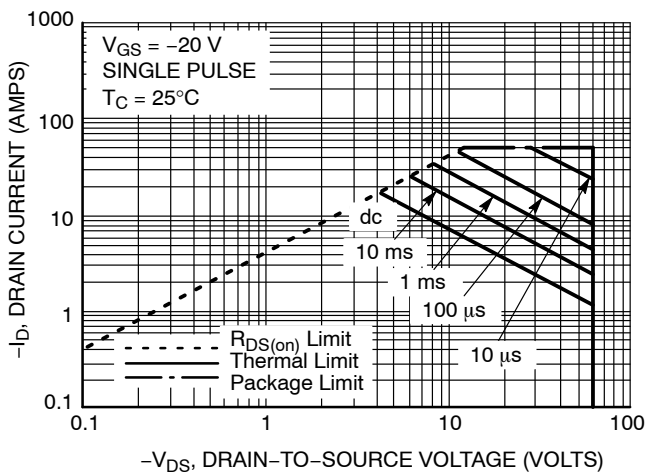
Figure 11. Maximum Rated Forward Biased Safe Operating Area
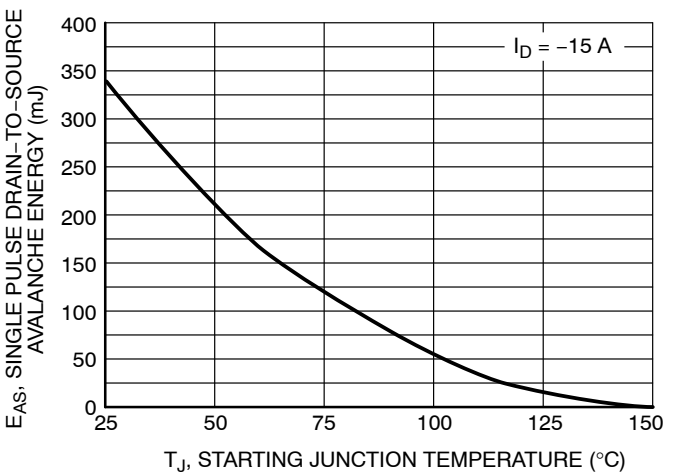
Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature
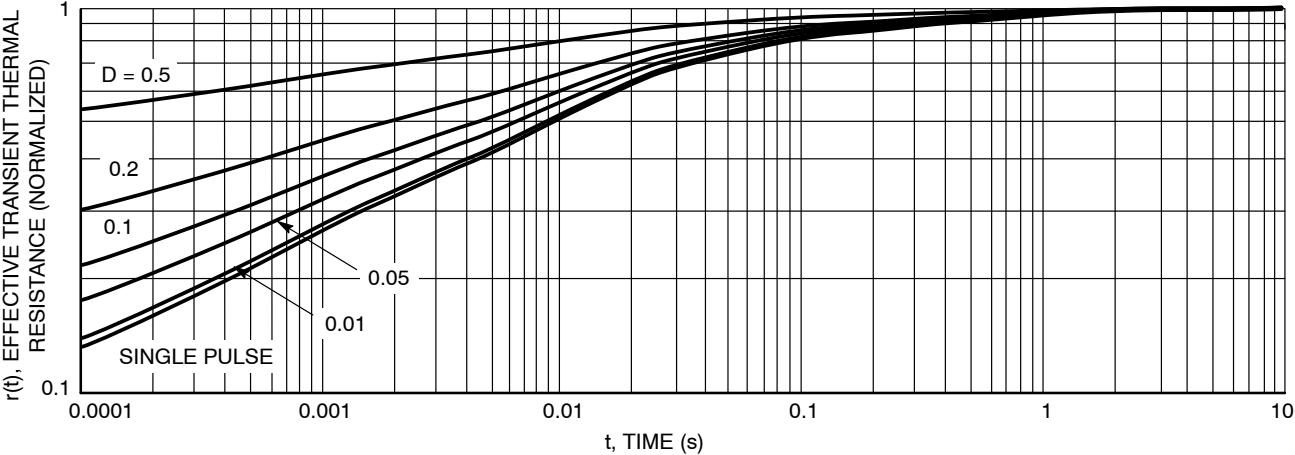
Figure 13. Thermal Response
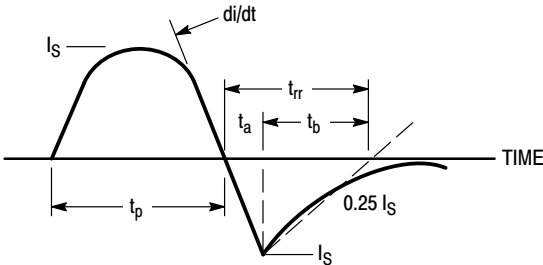
Figure 14. Diode Reverse Recovery Waveform

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®
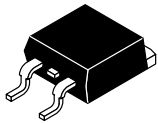
D²PAK 3
CASE 418B–04
ISSUE L

DATE 17 FEB 2015

SCALE 1:1
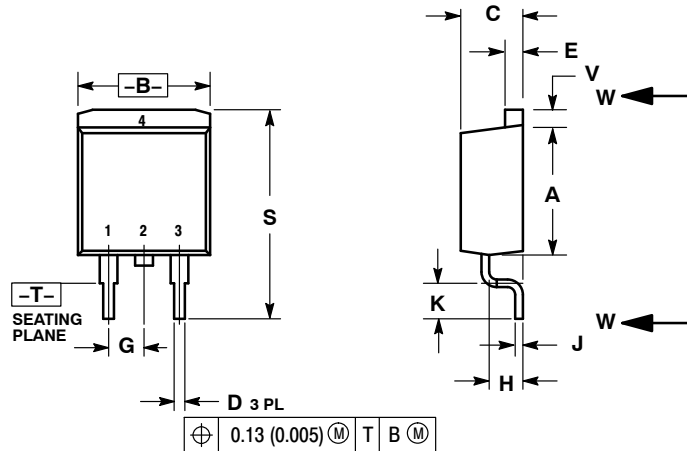
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B–01 THRU 418B–03 OBSOLETE, NEW STANDARD 418B–04.

⊕ | 0.13 (0.005) Ⓜ | T | B Ⓜ

SEATING PLANE

D 3 PL

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

VARIABLE CONFIGURATION ZONE

VIEW W–W 1

VIEW W–W 2

VIEW W–W 3

STYLE 1:
PIN 1. BASE
   2. COLLECTOR
   3. EMITTER
   4. COLLECTOR

STYLE 2:
PIN 1. GATE
   2. DRAIN
   3. SOURCE
   4. DRAIN

STYLE 3:
PIN 1. ANODE
   2. CATHODE
   3. ANODE
   4. CATHODE

STYLE 4:
PIN 1. GATE
   2. COLLECTOR
   3. EMITTER
   4. COLLECTOR

STYLE 5:
PIN 1. CATHODE
   2. ANODE
   3. CATHODE
   4. ANODE

STYLE 6:
PIN 1. NO CONNECT
   2. CATHODE
   3. ANODE
   4. CATHODE

MARKING INFORMATION AND FOOTPRINT ON PAGE 2

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DESCRIPTION:	**D²PAK 3**		**PAGE 1 OF 2**

D²PAK 3
CASE 418B–04
ISSUE L

**GENERIC
MARKING DIAGRAM***

IC	Standard	Rectifier
xx xxxxxxxxx AWLYWWG	xxxxxxxxG AYWW	AYWW xxxxxxxxG AKA
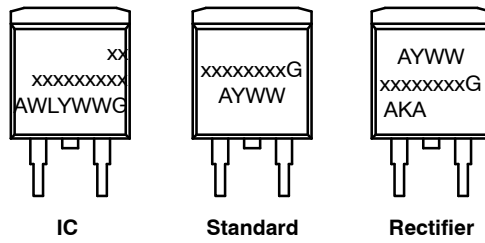
xx	= Specific Device Code
A	= Assembly Location
WL	= Wafer Lot
Y	= Year
WW	= Work Week
G	= Pb–Free Package
AKA	= Polarity Indicator

*This information is generic. Please refer to
  device data sheet for actual part marking.
  Pb–Free indicator, "G" or microdot " ▪ ",
  may or may not be present.

SOLDERING FOOTPRINT*

10.49

8.38

16.155

2X
3.504

2X
1.016

5.080
PITCH
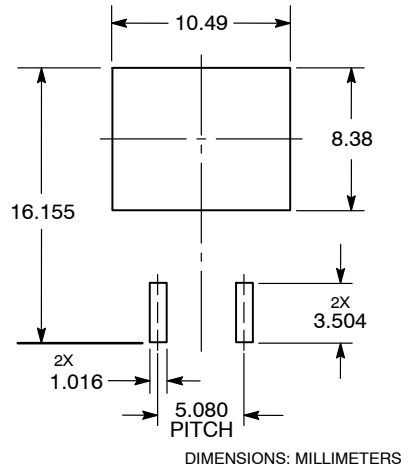
DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering
  details, please download the ON Semiconductor Soldering and
  Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	D²PAK 3		PAGE 2 OF 2

ADDITIONAL INFORMATION

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